



between respective steps of manufacturing said semiconductor device, said adsorbent being mounted detachably, and wherein said adsorbent is a silicon wafer with a surface having a Si-F bond.

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REMARKS

An Office Action was mailed on August 16, 2002. Claims 1 - 18 are pending in the present application. Applicants amend claims 1, 5, 10 and 15, and cancel claims 4, 8, 9, 14 and 18 without prejudice or disclaimer. No new matter is introduced.

OBJECTED CLAIMS

Claim 9 is objected to as being duplicative of claim 8. Applicant cancels claim 9 without prejudice or disclaimer, and respectfully requests that the objection be withdrawn.

Applicant thanks the Examiner for indicating that claims 5 and 15 are objected to as being respectively dependent on rejected base claims 1 and 10, but would be allowable if rewritten in independent form including all of the limitations of the associated base claim. Applicant amends claims 5 and 15 accordingly, and respectfully requests that the objection be withdrawn.

REJECTIONS UNDER 35 U.S.C. §§ 102, 103

Claims 1 - 4, 6 - 10, 12 - 14 and 16 - 18 are rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,346,518 to Baseman et al. Claim 11 is rejected

under 35 U.S.C. § 103(a) as being unpatentable over Baseman in view of U.S. Patent No. 6,093,947 to Hanafi et al. Applicant amends claims 1 and 10 to further clarify the nature of his invention, cancels claims 4, 8, 14 and 18 without prejudice or disclaimer, and respectfully traverses the above rejections.

Applicants' amended independent claims 1 and 10 respectively disclose an apparatus and method for semiconductor manufacture in which the a semiconductor substrate is stored in a stock/transfer vessel incorporating at least one adsorbent including at least one of an ion-exchange resin and a material with a surface having an Si-F bond.

Baseman discloses a vapor drain system for a semiconductor manufacturing process. The system of Baseman includes a vapor removal element 30 including an absorber layer 60 including one of sputtered titanium and activated carbon. Unlike Applicant's claimed device, however, Baseman does not disclose or suggest an adsorbent including one of an ion-exchange resin and a material with a surface having a Si-F bond. In addition, this claimed feature of Applicant's invention is neither disclosed nor suggested by Hanafi

Accordingly, Applicants' respectfully submit independent claims 1 and 10 stand in condition for allowance. As claims 2 – 3, 6 – 7, 11 – 13, and 16 – 17 depend from allowable claims 1 and 10, Applicant respectfully submits that claims 2 – 3, 6 – 7, 11 – 13, and 15 – 17 stand in condition for allowance for at least this reason.

CONCLUSION

An earnest effort has been made to be fully responsive to the Examiner's objections. In view of the above amendments and remarks, it is believed that 1 – 3, 5 – 7,



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10 - 13, and 15 - 17, consisting of independent claims 1, 5, 10 and 15 and the claims dependent therefrom, are in condition for allowance. Passage of this case to allowance is earnestly solicited. However, if for any reason the Examiner should consider this application not to be in condition for allowance, he is respectfully requested to telephone the undersigned attorney at the number listed below prior to issuing a further Action.

Attached is a marked up version of the changes made to the specification and claims by the current amendment. The attached pages are captioned **"Version With Markings To Show Changes Made"**.

Any fee due with this paper may be charged on Deposit Account 50-1290.

Respectfully submitted,

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MARKED-UP COPY OF AMENDED APPLICATION – S/N 09/614,874

IN THE CLAIMS

Please cancel claims 4, 8, 9, 14 and 18 without prejudice or disclaimer.

1. (Amended) A semiconductor substrate stock/transfer vessel, which is an openable/closeable sealed vessel used in a semiconductor device manufacturing process and adapted to store or transfer a semiconductor substrate,

wherein said vessel incorporates at least one adsorbent capable of adsorbing on organic substance, and said adsorbent is mounted detachably, and wherein said at least one adsorbent is at least one of an ion-exchange resin and a material with a surface having an Si-F bond.

5. (Amended) A semiconductor substrate stock/transfer vessel, which is an openable/closeable sealed vessel used in a semiconductor device manufacturing process and adapted to store or transfer a semiconductor substrate,

wherein said vessel incorporates at least one adsorbent capable of adsorbing on organic substance, and said adsorbent is mounted detachably [A vessel according to claim 1,] and wherein said adsorbent is a silicon wafer with a surface having a Si-F bond.

10. (Amended) A method of manufacturing a semiconductor device wherein a semiconductor substrate is stored in a stock/transfer vessel incorporating at least one adsorbent capable of adsorbing an organic substance during an operation wait time between respective steps of manufacturing said semiconductor device, said adsorbent

being mounted detachably, and wherein said at least one adsorbent is selected to be at least one of an ion-exchange resin and a material with a surface having an Si-F bond.

15. (Amended) A method of manufacturing a semiconductor device wherein a semiconductor substrate is stored in a stock/transfer vessel incorporating at least one adsorbent capable of adsorbing an organic substance during an operation wait time between respective steps of manufacturing said semiconductor device, said adsorbent being mounted detachably [A method according to claim 10,] and wherein said adsorbent is a silicon wafer with a surface having a Si-F bond.